

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

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# 2SK3234

Silicon N Channel MOS FET  
High Speed Power Switching

**RENESAS**

ADE-208-1370 (Z)

1st. Edition

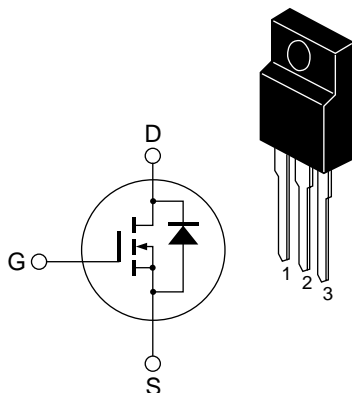
Mar. 2001

## Features

- Low on-resistance:  $R_{DS(on)} = 0.65 \Omega$  typ.
- Low leakage current:  $IDSS = 1 \mu A$  max (at  $V_{DS} = 500 V$ )
- High speed switching:  $t_f = 25 ns$  typ (at  $V_{GS} = 10 V$ ,  $V_{DD} = 250 V$ ,  $I_D = 4 A$ )
- Low gate charge:  $Q_g = 25 nC$  typ (at  $V_{DD} = 400 V$ ,  $V_{GS} = 10 V$ ,  $I_D = 8 A$ )
- Avalanche ratings

## Outline

TO-220CFM



1. Gate
2. Drain
3. Source

## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	500	V
Gate to source voltage	$V_{GSS}$	$\pm 30$	V
Drain current	$I_D$	8	A
Drain peak current	$I_{D (pulse)}^{Note1}$	32	A
Body-drain diode reverse drain current	$I_{DR}$	8	A
Body-drain diode reverse drain peak current	$I_{DR (pulse)}^{Note1}$	32	A
Avalanche current	$I_{AP}^{Note3}$	8	A
Channel dissipation	$P_{ch}^{Note2}$	35	W
Channel to case Thermal Impedance	$\theta_{ch-c}$	3.57	°C/W
Channel temperature	$T_{ch}$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

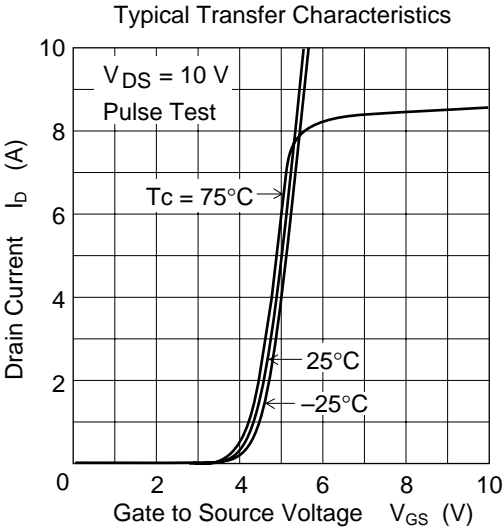
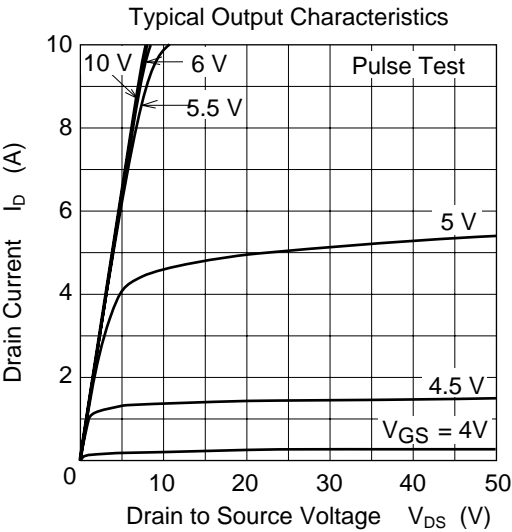
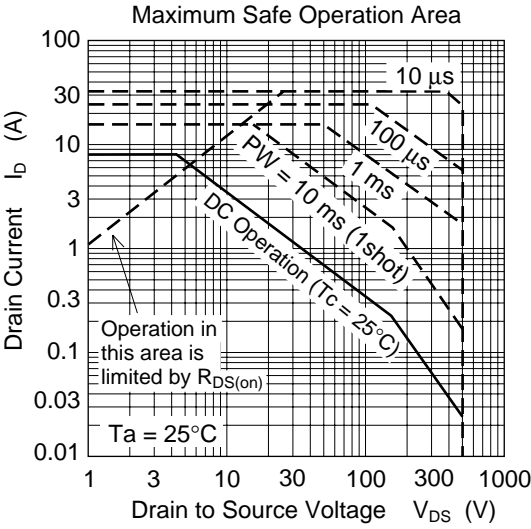
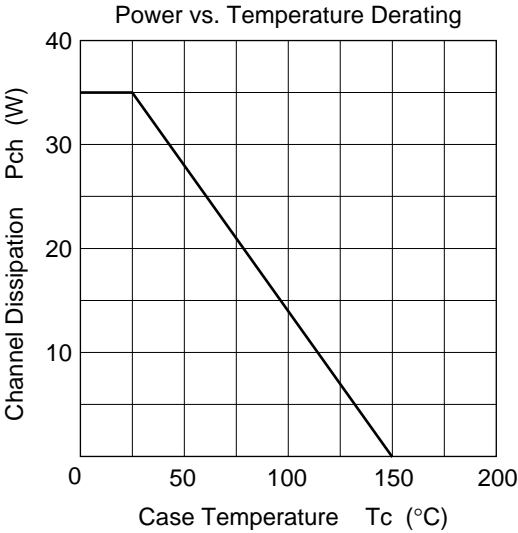
Notes: 1.  $PW \leq 10 \mu s$ , duty cycle  $\leq 1\%$ 2. Value at  $T_c = 25^\circ C$ 3.  $T_{ch} \leq 150^\circ C$

**Electrical Characteristics (Ta = 25°C)**

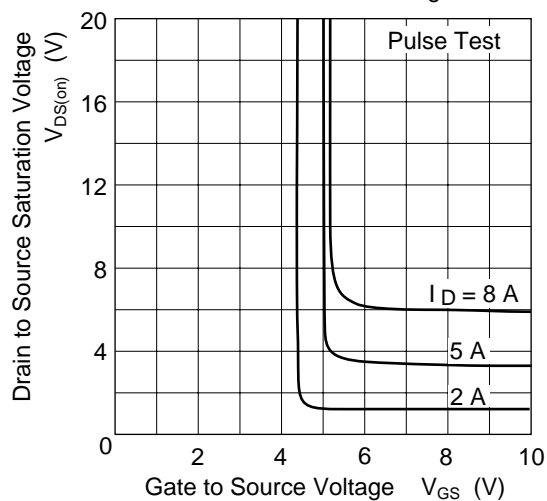
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	—	—	V	$I_D = 10 \text{ mA}$ , $V_{GS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	$\pm 0.1$	$\mu\text{A}$	$V_{GS} = \pm 30 \text{ V}$ , $V_{DS} = 0$
Zero gate voltage drain current	$I_{DSS}$	—	—	1	$\mu\text{A}$	$V_{DS} = 500 \text{ V}$ , $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	—	4.0	V	$V_{DS} = 10 \text{ V}$ , $I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.65	0.85	$\Omega$	$I_D = 4 \text{ A}$ , $V_{GS} = 10 \text{ V}$ <sup>Note4</sup>
Forward transfer admittance	$ y_{fs} $	4.0	7.0	—	S	$I_D = 4 \text{ A}$ , $V_{DS} = 10 \text{ V}$ <sup>Note4</sup>
Input capacitance	$C_{iss}$	—	970	—	pF	$V_{DS} = 25 \text{ V}$
Output capacitance	$C_{oss}$	—	110	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	$C_{rss}$	—	18	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	25	—	ns	$I_D = 4 \text{ A}$
Rise time	$t_r$	—	21	—	ns	$V_{GS} = 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	80	—	ns	$R_L = 62.5 \Omega$
Fall time	$t_f$	—	25	—	ns	$R_g = 10 \Omega$
Total gate charge	$Q_g$	—	25	—	nC	$V_{DD} = 400 \text{ V}$
Gate to source charge	$Q_{gs}$	—	4	—	nC	$V_{GS} = 10 \text{ V}$
Gate to drain charge	$Q_{gd}$	—	11	—	nC	$I_D = 8 \text{ A}$
Body-drain diode forward voltage	$V_{DF}$	—	0.9	1.35	V	$I_F = 8 \text{ A}$ , $V_{GS} = 0$
Body-drain diode reverse recovery time	$t_{rr}$	—	360	—	ns	$I_F = 8 \text{ A}$ , $V_{GS} = 0$
Body-drain diode reverse recovery charge	$Q_{rr}$	—	1.7	—	$\mu\text{C}$	$diF/dt = 100 \text{ A}/\mu\text{s}$

Note: 4. Pulse test

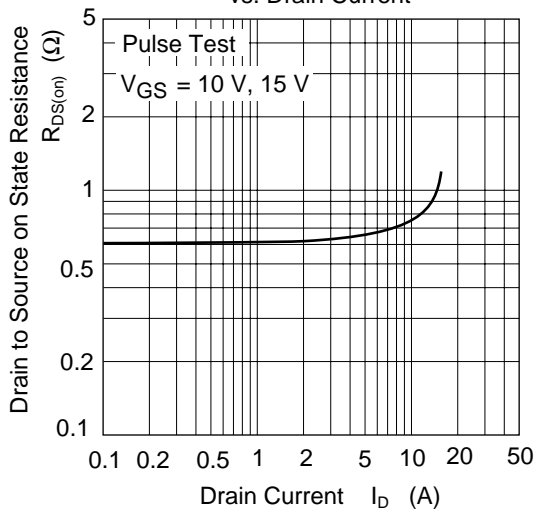
Main Characteristics



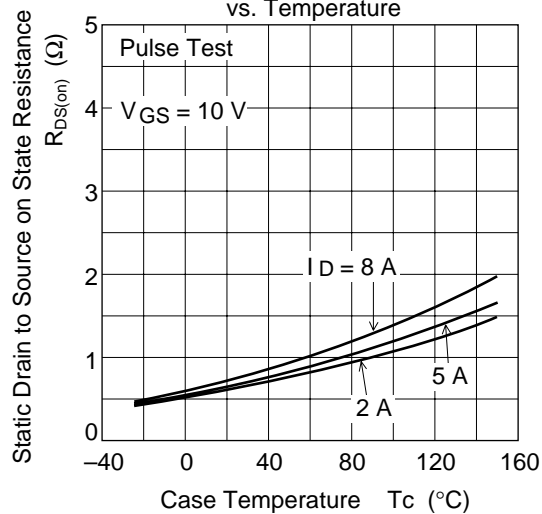
Drain to Source Saturation Voltage vs.  
Gate to Source Voltage



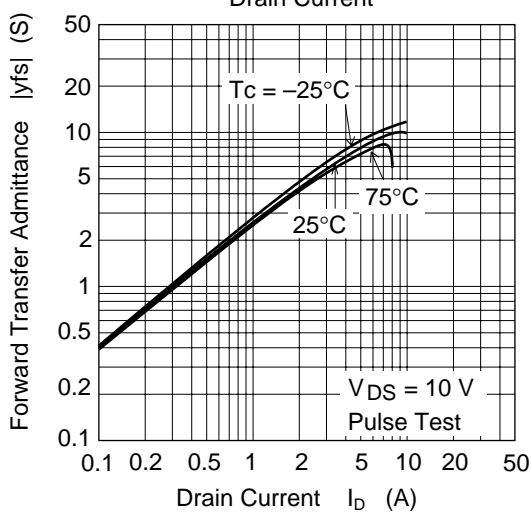
Static Drain to Source on State Resistance  
vs. Drain Current



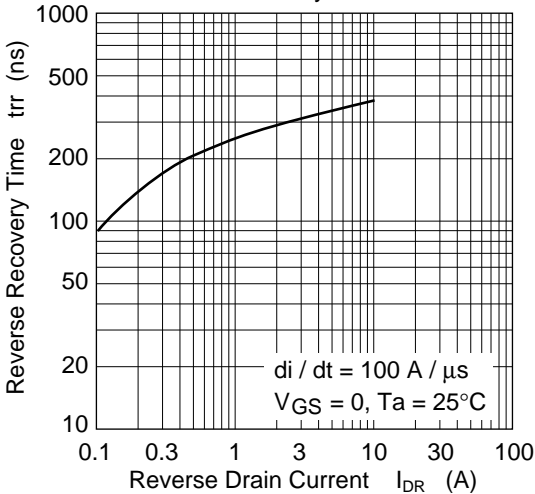
Static Drain to Source on State Resistance  
vs. Temperature



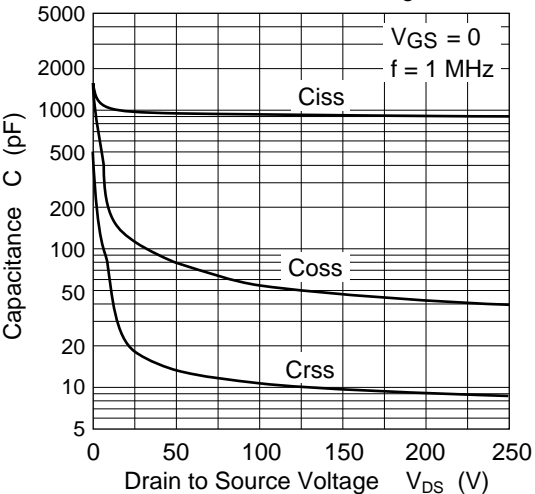
Forward Transfer Admittance vs.  
Drain Current



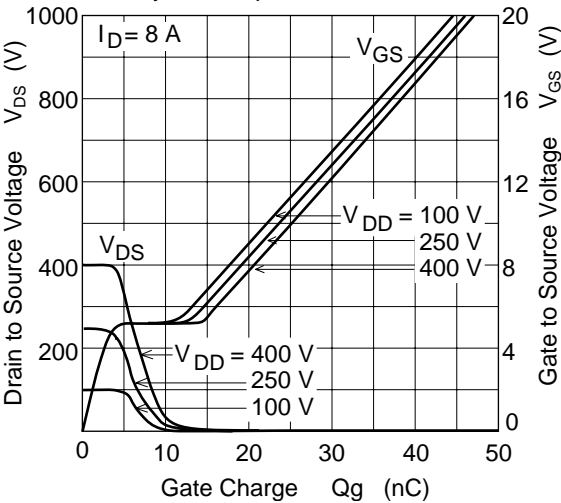
Body-Drain Diode Reverse Recovery Time



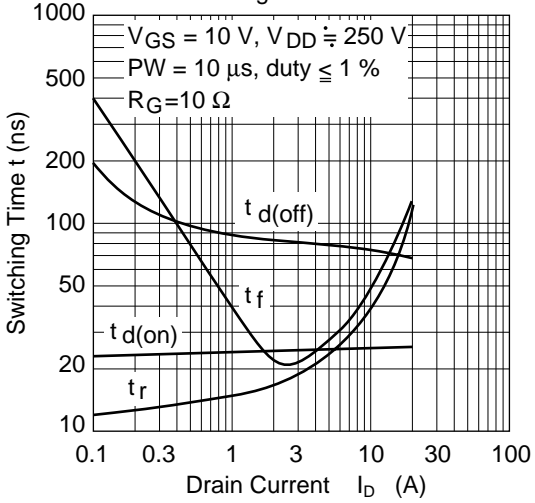
Typical Capacitance vs. Drain to Source Voltage



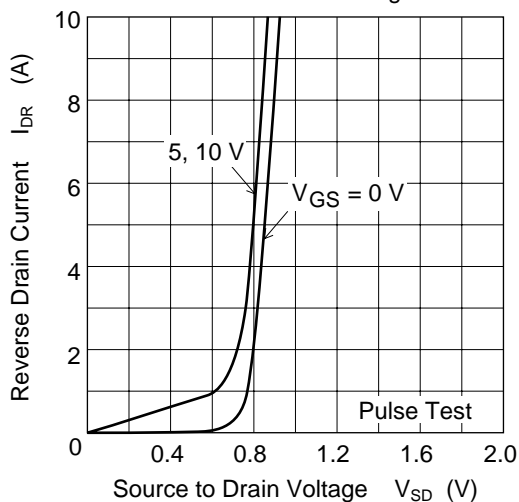
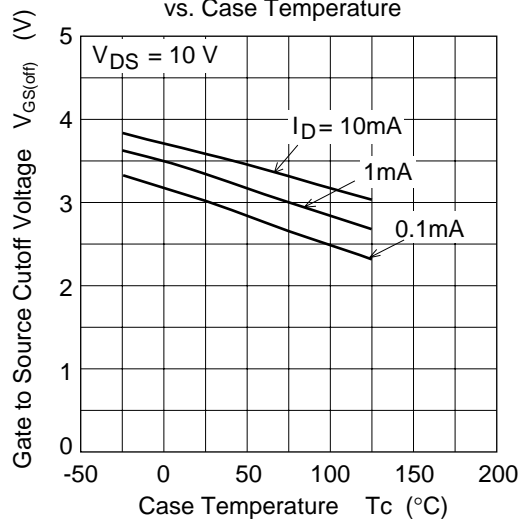
Dynamic Input Characteristics



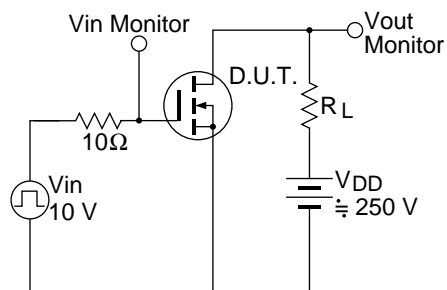
Switching Characteristics



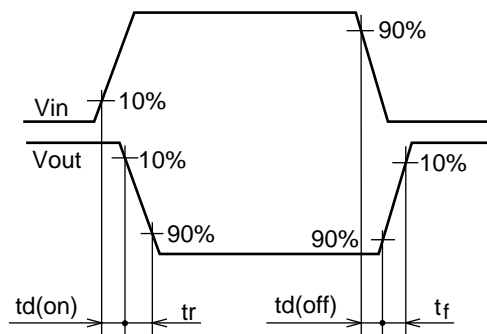


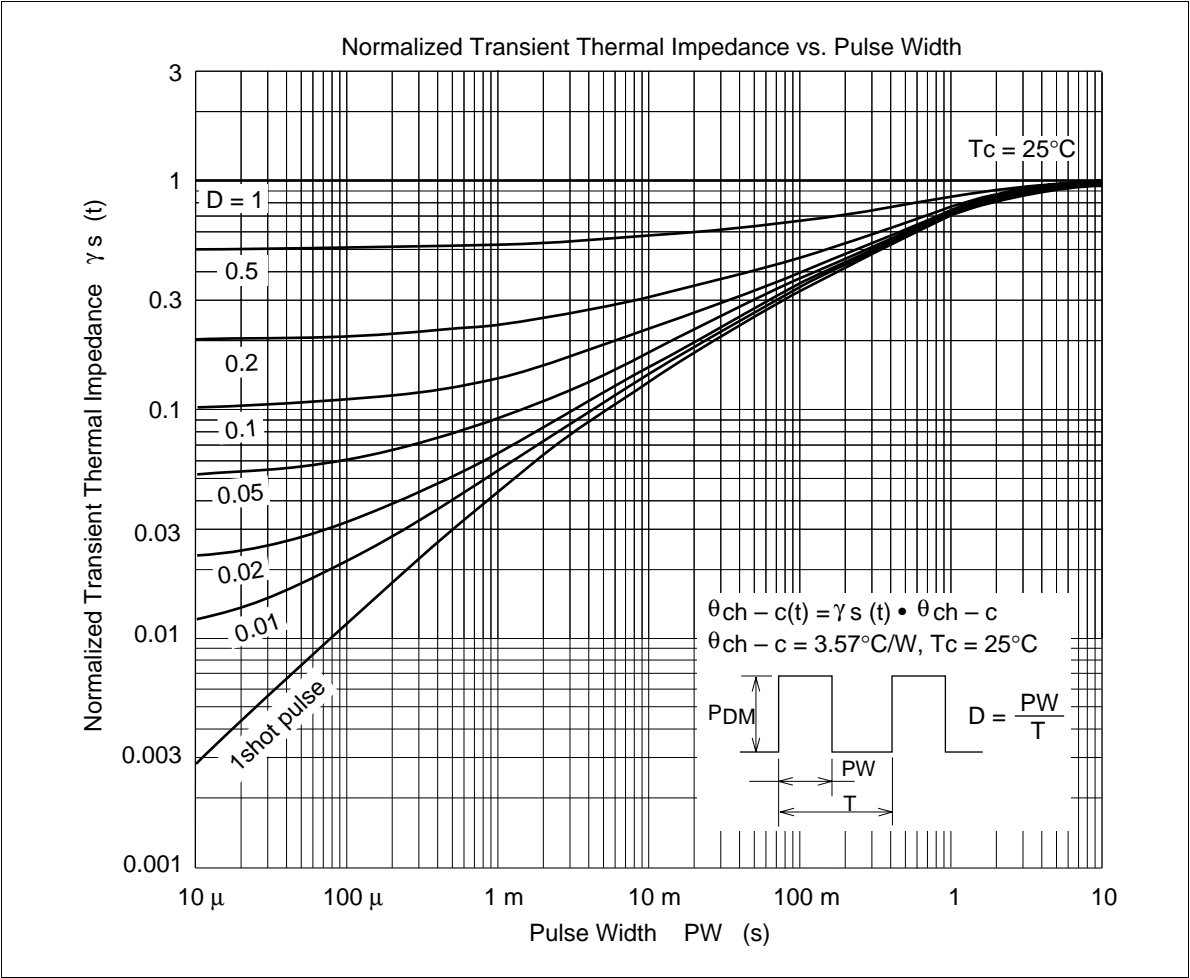
Reverse Drain Current vs.  
Source to Drain VoltageGate to Source Cutoff Voltage  
vs. Case Temperature

Switching Time Test Circuit



Waveform

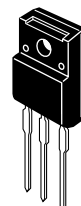
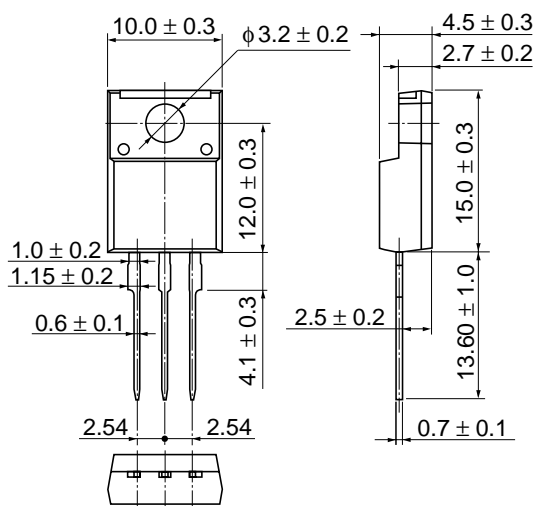




## Package Dimensions

As of January, 2001

Unit: mm



Hitachi Code	TO-220CFM
JEDEC	—
EIAJ	—
Mass (reference value)	1.9 g

## Cautions

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